MOSFETs Silicon N-channel MOS (U-MOSIV)

TPCP8207

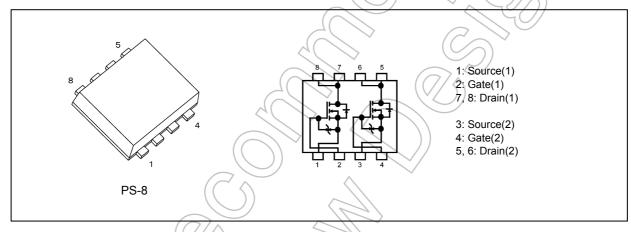
1. Applications

- · Motor Drivers
- · Mobile Equipment

2. Features

- (1) AEC-Q101 qualified
- (2) Small footprint due to a small and thin package
- (3) Small gate charge : $Q_{SW} = 4.7 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 29.1 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (5) Low leakage current: I_{DSS} = 10 μA (max) (V_{DS} = 40 V)
- (6) Enhancement mode: $V_{th} = 2$ to 3 V ($V_{DS} = 10$ V, $I_{D} = 1$ mA)

3. Packaging and Internal Circuit





4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Rating	Unit		
Drain-source voltage			V_{DSS}	40	V
Gate-source voltage			V _{GSS}	±20	
Drain current (DC)		(Note 1)	√I _D	5	Α
Drain current (pulsed)		(Note 1)	IDP	20	
Power dissipation (single operation)	(t = 5 s)	(Note 2), (Note 4)	P _{D(1)}	1.77	W
Power dissipation (per device for dual operation)	(t = 5 s)	(Note 2), (Note 5)	P _{D(2)}	1.47	
Power dissipation (single operation)	(t = 5 s)	(Note 3), (Note 4)	P _{D(1)}	0.69	
Power dissipation (per device for dual operation)	(t = 5 s)	(Note 3), (Note 5)	P _{D(2)}	0.43	
Single-pulse avalanche energy		(Note 6)	E _{AS}	33.2	mJ
Avalanche current) VI _{AR}	5	Α
Channel temperature		(Note 7)	T _{ch}	175	°C
Storage temperature		(Note 7)	T _{stg}	-55 to 175	

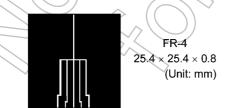
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

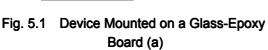
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

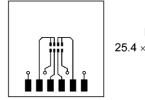
5. Thermal Characteristics

Charact	eristics Symbol Max	Unit
Channel-to-ambient thermal resistance (single operation	n) (t = 5 s) (Note 2), (Note 4) R _{th(ch-a)(1)} 84.7	°C/W
Channel-to-ambient thermal resistance (per device for operation)	dual (t = 5 s) (Note 2), (Note 5) R _{th(ch-a)(2)} 102	
Channel-to-ambient thermal resistance (single operation	n) $(t = 5 s)$ (Note 3), (Note 4) $R_{th(ch-a)(1)}$ 217.3	
Channel-to-ambient thermal resistance (per device for operation)	dual (t=5s) (Note 3), (Note 5) R _{th(ch-a)(2)} 348.8	

- Note 1: Ensure that the channel temperature does not exceed 175 °C.
- Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1
- Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2
- Note 4: Power dissipation and thermal resistance values per device with the other device being off (During single operation, power is supplied to only one of the two devices.)
- Note 5: Power dissipation and thermal resistance values per device for dual operation (During dual operation, power is evenly supplied to both devices.)
- Note 6: V_{DD} = 25 V, T_{ch} = 25 °C (initial), L = 1.379 mH, R_G = 1 Ω , I_{AR} = 5 A
- Note 7: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.







FR-4 $25.4 \times 25.4 \times 0.8$ (Unit: mm)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	7	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	40	_	_	V
	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	20) ~		
Gate threshold voltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2	2.5	3	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 6 V, I _D = 2.5 A	/ \	39.3	62.8	mΩ
		V _{GS} = 10 V, I _D = 2.5 A)	29.1	36.3	

6.2. Dynamic Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	- 1	505		pF
Reverse transfer capacitance	C _{rss}	((// \) \ \	_((66	<u></u>	
Output capacitance	C _{oss}		K	(115)) —	
Switching time (rise time)	t _r	See Figure 6.2.1.	<u> </u>	5.4	_	ns
Switching time (turn-on time)	t _{on}			12		
Switching time (fall time)	t _f		//-//	4.3	_	
Switching time (turn-off time)	t _{off}			17.4	_	

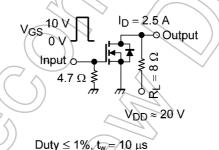


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	11.8	_	nC
Gate-source charge 1	Q _{gs1}		_	2.1	_	
Gate-drain charge	Q _{gd}		_	3.9	_	
Gate switch charge	Q _{SW}		_	4.7	_	

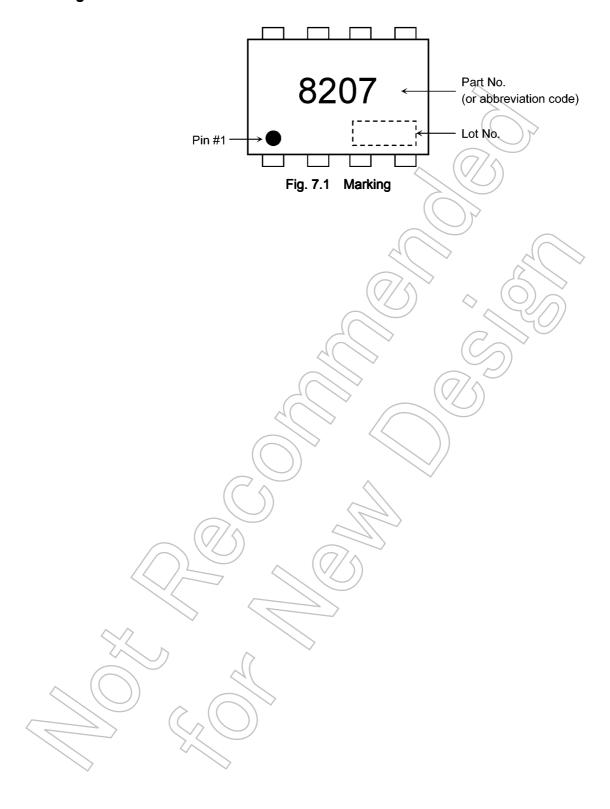
6.4. Source-Drain Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note	8) I _{DRP}	_	_	_	20	Α
Diode forward voltage	V_{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.2	V

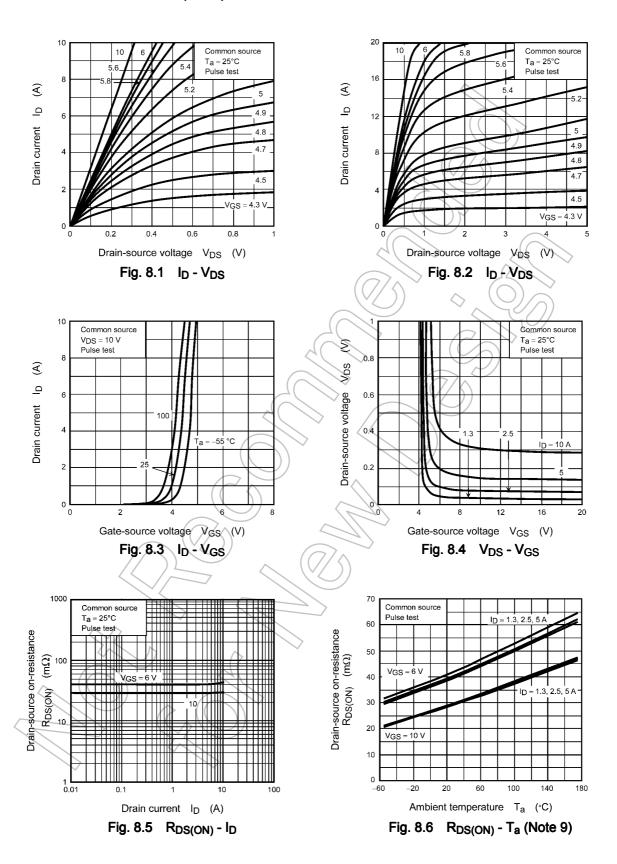
Note 8: Ensure that the channel temperature does not exceed 175 °C.



7. Marking



8. Characteristics Curves (Note)



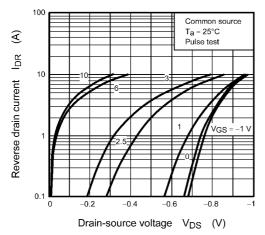


Fig. 8.7 I_{DR} - V_{DS}

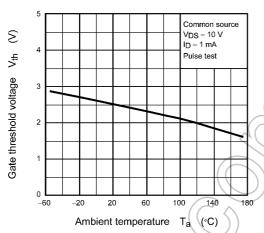


Fig. 8.9 V_{th} - T_a (Note 9)

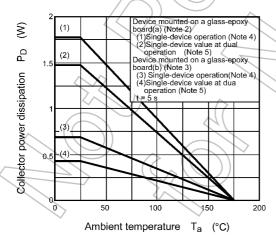


Fig. 8.11 P_D - T_a (Note 9) (Guaranteed Maximum)

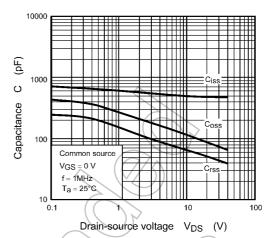


Fig. 8.8 Capacitance - V_{DS}

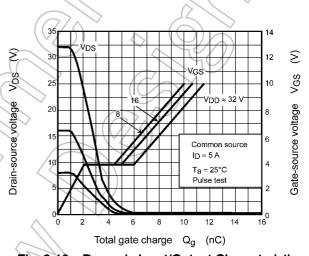


Fig. 8.10 Dynamic Input/Output Characteristics

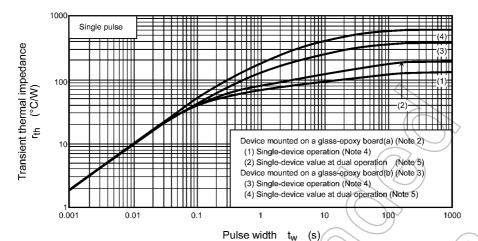


Fig. 8.12 r_{th} - t_w (Guaranteed Maximum)

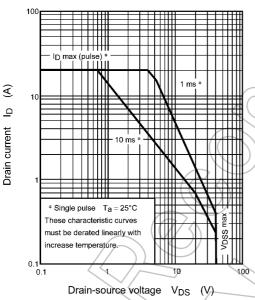


Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

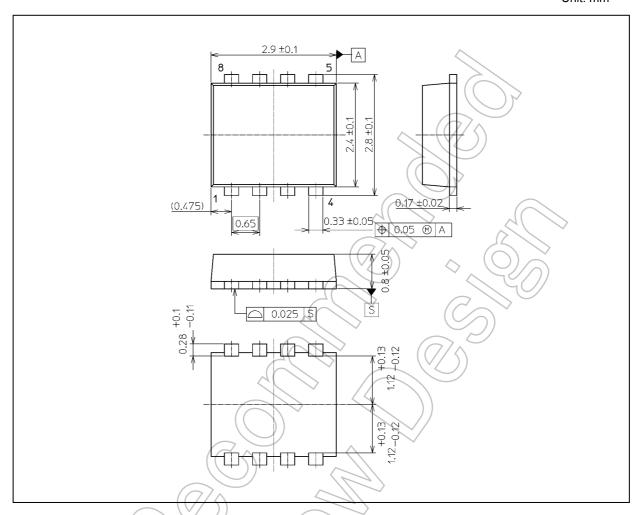
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Note 9: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

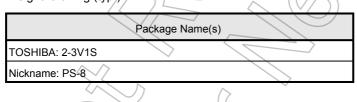


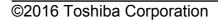
Package Dimensions

Unit: mm



Weight: 0.017 g (typ.)





Rev.5.0



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